

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Number 0353120260 Part Weight 0.275G

Part Name 2.5 PITCH W/B CONN WAFER ASSY

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)	
2.5 PITCH W/B CONN WAFER ASSY	Assembly		100	0.275	
2.5 PITCH W/B CONN WAFER	Component		77.4545	0.213	
PA66-GF20	Material		77.4545	0.213	
PA66	Substance		41.8255	0.11502	
GF-Fibre	Substance		15.4909	0.0426	
Flame Retardant, ISO 1043-4 FR(17)	Substance		13.1673	0.03621	
Antimonytrioxide	Substance	1309-64-4	5.4218	0.01491	
Further Additives, not to declare	Substance	system	1.5491	0.00426	
0.635 SQ WIRE PIN(PLATED)	Assembly		22.5455	0.062	
. SQ WIRE PIN(UNPLAT)	Component		22.5455	0.062	
C2700	Material		22.5455	0.062	
Copper	Substance	7440-50-8	14.6545	0.0403	
Zinc (metal)	Substance	7440-66-6	7.8796	0.021669	

Form Rev - F

Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Lead	Substance	7439-92-1	0.0056	0.000016
Iron	Substance	7439-89-6	0.0056	0.000016

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2021)4569-DC (8 July 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	C2700	*Note	250	Yes
Antimonytrioxide	PA66-GF20	*Note	70,000	Yes
copper	C2700	*Note	650,000	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Form Rev - F

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Exemptions

Part Name	Exemption
C2700	44 Concentration within acceptable GADSL limits

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Bromine and its compounds	PA66-GF20	900	170,000	Yes
Bromine and Chlorine combined	PA66-GF20	1,500	170,000	Yes

China ROHS Declaration Information

Part Number 0353120260							
Part Name 2.5 PITCH W/B CONN WAFER ASSY	(e)						
Part Information			Ha	zardous S	Substance	s	
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
2.5 PITCH W/B CONN WAFER ASSY		0	0	0	0	0	0
2.5 PITCH W/B CONN WAFER		0	0	0	0	0	0
0.635 SQ WIRE PIN(PLATED)		0	0	0	0	0	0
. SQ WIRE PIN(UNPLAT)		0	0	0	0	0	0

Additional Information

Annex XVII to REACH (76/769/EEC)	Compliant
Regulation (EU) 2019/1021 (POP)	Compliant

Form Rev - F

Process Information

Component Plating / Surface Finish	SnCu
Termination Base Alloy	Brass
Solder Alloy	SnAgCu
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Oct 7, 2021